

## IN THE CLAIMS

Please cancel claims 1-14 and 33-50. Please add the following new claims 51-73.

1-14. (Cancelled)

33-50. (Cancelled)

51. (New) A semiconductor die package, comprising:

an encapsulant body having opposed top and bottom surfaces and side surfaces  
vertically between the top and bottom surfaces;

inner leads each having an inner first and an outer second end, the first and second  
ends being within the encapsulant body;

outer leads each having an inner portion within the encapsulant body and an outer  
portion extending outside of the encapsulant body;

a die paddle within the encapsulant body,

wherein the inner leads and the die paddle are downset in the encapsulant body  
from the encapsulated inner portions of the outer leads, a bottom surface portion of  
each of the inner leads and the die paddle is exposed at the bottom surface of the  
encapsulant body, and the unencapsulated outer portion of each of the outer leads  
includes a bottom surface portion that is approximately coplanar with the bottom  
surface of the encapsulant body and the exposed bottom surface portions of the die  
paddle and inner leads; and

a semiconductor die within the encapsulant body, mounted on the inner leads, and  
electrically coupled to the inner leads and to the inner portion of the outer leads.

52. (New) The package of Claim 51, wherein an inner end of the encapsulated inner  
portion of the outer leads does not extend inwardly beyond the second end of the inner leads.

53. (New) The package of Claim 51, wherein an inner end of the encapsulated inner portion of the outer leads extends inwardly beyond the second end of the inner leads.

54. (New) The package of claim 51, further comprising an encapsulated layer of an insulative tape coupled across the inner leads and disposed between the inner leads and the semiconductor die.

55. (New) The package of claim 51, further comprising an encapsulated layer of an insulative tape coupled across the inner leads, wherein the inner leads are disposed between the layer of the insulative tape and the semiconductor die.

56. (New) The package of claim 51, wherein the inner leads include an encapsulated second bottom surface portion that is adjacent to the exposed bottom surface portion of the inner lead.

57. (New) The package of claim 51, wherein the inner leads are planar between the first and second ends.

58. (New) A semiconductor die package, comprising:  
an encapsulant body having opposed top and bottom surfaces and side surfaces  
vertically between the top and bottom surfaces;  
inner leads each having an inner first end and an outer second end, the first and second ends being within the encapsulant body;

outer leads each having an encapsulated inner portion within the encapsulant body and an unencapsulated outer portion that extends outward from the side surface of the encapsulant body;

wherein a bottom surface portion of each of the inner leads and the die paddle is exposed at the bottom surface of the encapsulant body, and the unencapsulated outer portion of each of the outer leads is vertically bent so as to have a bottom surface portion that is approximately coplanar with the bottom surface of the encapsulant body and the exposed bottom surface portions of the inner leads; and  
a semiconductor die within the encapsulant body and electrically coupled to the inner leads and to the inner portion of the outer leads.

59. (New) The package of Claim 58, wherein an inner end of the encapsulated inner portion of the outer leads does not extend inwardly beyond the second end of the inner leads.

60. (New) The package of Claim 58, wherein an inner end of the encapsulated inner portion of the outer leads extends inwardly beyond the second end of the inner leads.

61. (New) The package of claim 58, further comprising an encapsulated layer of an insulative tape coupled across the inner leads and disposed between the inner leads and the semiconductor die.

62. (New) The package of claim 58, further comprising an encapsulated layer of an insulative tape coupled across the inner leads, wherein the inner leads are disposed between the layer of the insulative tape and the semiconductor die.

63. (New) The package of claim 58, wherein the inner leads include an encapsulated second bottom surface portion that is adjacent to the exposed bottom surface portion of the inner lead.

64. (New) The package of claim 58, wherein the inner leads are planar between the first and second ends.

65. (New) A semiconductor die package, comprising:  
an encapsulant body having opposed first and second surfaces and side surfaces vertically between the first and second surfaces;  
inner leads each having an inner first end and an outer second end, the first and second ends being within the encapsulant body;  
outer leads each having an encapsulated inner portion within the encapsulant body and an unencapsulated outer portion that extends outward from the side surface of the encapsulant body;  
wherein a surface portion of each of the inner leads is exposed at the first surface of the encapsulant body, and the unencapsulated outer portion of each of the outer leads is vertically bent so as to have a surface portion that is approximately coplanar with one of the first and second surfaces of the encapsulant body;  
a semiconductor die within the encapsulant body, mounted on the inner leads and the die paddle by an adhesive layer, and electrically coupled to the inner leads and to the inner end portion of the outer leads.

66. (New) The package of Claim 65, wherein an inner end of the encapsulated inner portion of the outer leads does not extend inwardly beyond the second end of the inner leads.

67. (New) The package of Claim 65, wherein an inner end of the encapsulated inner portion of the outer leads extends inwardly beyond the second end of the inner leads.

68. (New) The package of claim 65, further comprising an encapsulated layer of an insulative tape coupled across the inner leads and disposed between the inner leads and the semiconductor die.

69. (New) The package of claim 65, further comprising an encapsulated layer of an insulative tape coupled across the inner leads, wherein the inner leads are disposed between the layer of the insulative tape and the semiconductor die.

70. (New) The package of claim 65, wherein the inner leads include an encapsulated second bottom surface portion that is adjacent to the exposed bottom surface portion of the inner lead.

71. (New) The package of claim 65, wherein the inner leads are planar between the first and second ends.

72. (New) The package of claim 65, wherein the unencapsulated outer portion of each of the outer leads is bent so as to have a surface portion that is approximately coplanar with the first surface of the encapsulant body.

73. (New) The package of claim 65, wherein the unencapsulated outer portion of each of the outer leads is bent so as to have a surface portion that is approximately coplanar with the second surface of the encapsulant body.